# Detector technologies (my personal view)

Eva Vilella
University of Liverpool
vilella@hep.ph.liv.ac.uk

# My background



Dr. Eva Vilella
UKRI Research Fellow
University of Liverpool

 PhD @ Barcelona
 2010 – 2013

 PDRA @ Liverpool
 2014 – 2019

 Future Leaders Fellow @ Liverpool
 2019 – now

- Mostly High Voltage CMOS sensors R&D (chip design and evaluation)
  - LHCb Mighty Tracker Upgrade
  - CERN-RD50 CMOS Working Group (ie generic R&D), which I started and lead
  - proton EDM
  - ATLAS ITk Upgrade
  - Mu3e

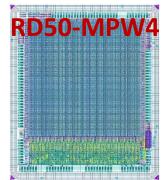


- ILC
- CLIC

and developed IP for a readout chip for DEPFET sensors

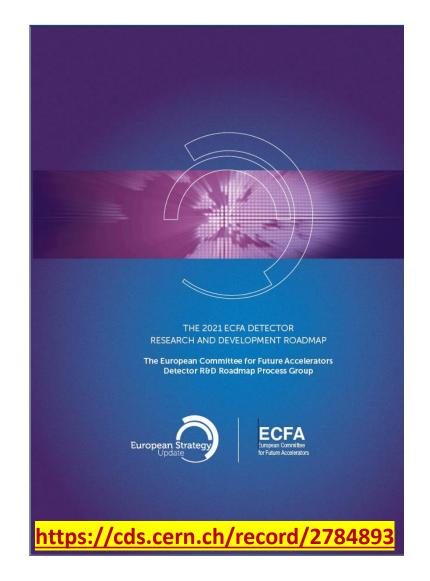
- Belle II





# **2021 ECFA Detector R&D Roadmap**

- Developed by the community to balance the detector R&D efforts in Europe
- Highlighted the need for a new R&D phase in the form of Detector Research and Development (DRD) collaborations
- To enhance the performance of the particle physics programme in the near and long term





# **Detector Research and Development Themes (DRDTs)**

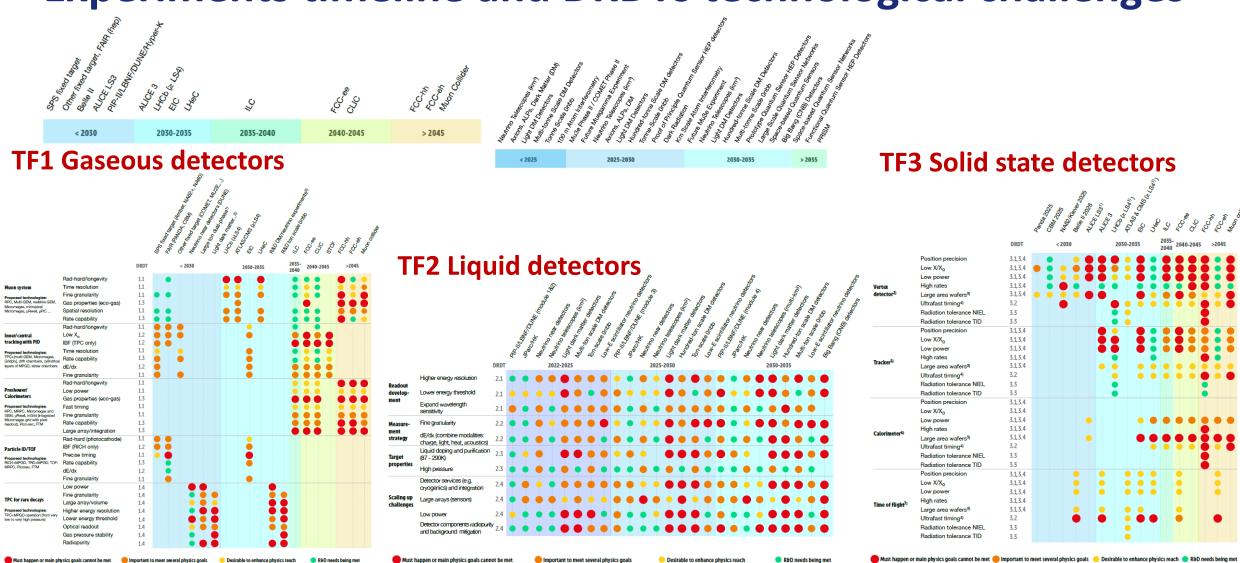
From 01.01.2024

|         |          | an large on section was severe assess   |
|---------|----------|---|
|         | DRDT 1.1 | Improve time and spatial resolution for gaseous detectors with<br>long-term stability   |
| Gaseous | DRDT 1.2 | Achieve tracking in gaseous detectors with dE/dx and dN/dx capability<br>in large volumes with very low material budget and different read-out<br>schemes |
|         | DRDT1.3  | Develop environmentally friendly gaseous detectors for very large<br>areas with high-rate capability  |
|         | DRDT1.4  | Achieve high sensitivity in both low and high-pressure TPCs   |
|         | DRDT 2.1 | Develop readout technology to increase spatial and energy resolution for liquid detectors   |
| Liquid  | DRDT 2.2 | Advance noise reduction in liquid detectors to lower signal energy thresholds   |
| Liquiu  | DRDT 2.3 | Improve the material properties of target and detector components in liquid detectors   |
|         | DRDT 2.4 | Realise liquid detector technologies scalable for integration in<br>large systems   |
|         | DRDT 3.1 | Achieve full integration of sensing and microelectronics in monolithic CMOS pixel sensors   |
| Solid   | DRDT 3.2 | Develop solid state sensors with 4D-capabilities for tracking and<br>calorimetry  |
| state   | DRDT 3.3 | Extend capabilities of solid state sensors to operate at extreme<br>fluences  |
|         | DRDT 3.4 | Develop full 3D-interconnection technologies for solid state devices<br>in particle physics   |
| PID and | DRDT 4.1 | Enhance the timing resolution and spectral range of photon detectors  |
| Photon  | DRDT 4.2 | Develop photosensors for extreme environments   |
|         | DRDT 4.3 | Develop RICH and imaging detectors with low mass and high resolution timing   |
|         | DRDT 4.4 | Develop compact high performance time-of-flight detectors   |
|         | DRDT 5.1 | Promote the development of advanced quantum sensing technologies  |
| 1100000 | DRDT 5.2 | Investigate and adapt state-of-the-art developments in quantum  |
| Quantum | DRDT 5.3 | technologies to particle physics Establish the necessary frameworks and mechanisms to allow exploration of emerging technologies                          |
|         | DRDT 5.4 | Develop and provide advanced enabling capabilities and infrastructure   |
|         |          |   |

- The roadmap identified several R&D themes
- Critical to achieve the scientific programme in the ESPP (European Strategy for Particle Physics)
- Derived from the technological challenges that need to be overcome for the scientific potential of the future facilities

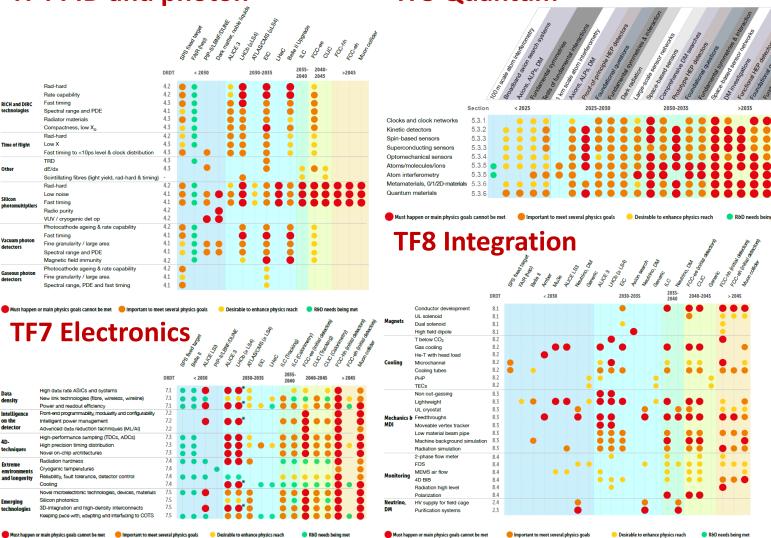
|             | DRDT 6.1 | Develop radiation-hard calorimeters with enhanced electromagnetic<br>energy and timing resolution  |
|-------------|----------|--|
| Calorimetry | DRDT 6.2 | Develop high-granular calorimeters with multi-dimensional readout<br>for optimised use of particle flow methods                          |
|             | DRDT 6.3 | Develop calorimeters for extreme radiation, rate and pile-up environments  |
|             | DRDT7.1  | Advance technologies to deal with greatly increased data density   |
|             | DRDT7.2  | Develop technologies for increased intelligence on the detector  |
| lactronics  | DRDT7.3  | Develop technologies in support of 4D- and 5D-techniques   |
|             | DRDT7.4  | Develop novel technologies to cope with extreme environments and required longevity  |
|             | DRDT7.5  | Evaluate and adapt to emerging electronics and data processing<br>technologies   |
|             | DRDT 8.1 | Develop novel magnet systems   |
|             | DRDT 8.2 | Develop improved technologies and systems for cooling  |
| ntegration  | DRDT 8.3 | Adapt novel materials to achieve ultralight, stable and high<br>precision mechanical structures. Develop Machine Detector<br>Interfaces. |
|             | DRDT 8.4 | Adapt and advance state-of-the-art systems in monitoring<br>including environmental, radiation and beam aspects                          |
| Training    | DCT1     | Establish and maintain a European coordinated programme for training in<br>instrumentation   |
|             | DCT 2    | Develop a master's degree programme in instrumentation   |

# **Experiments timeline and DRDTs technological challenges**

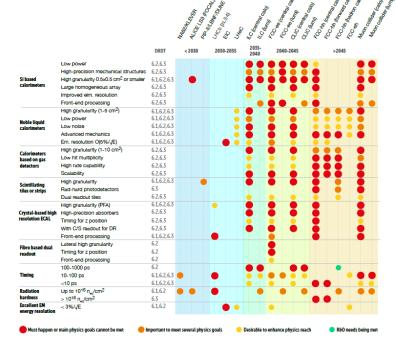


# **Experiments timeline and DRDTs technological challenges**

TF4 PID and photon TF5 Quantum



### **TF6 Calorimetry**



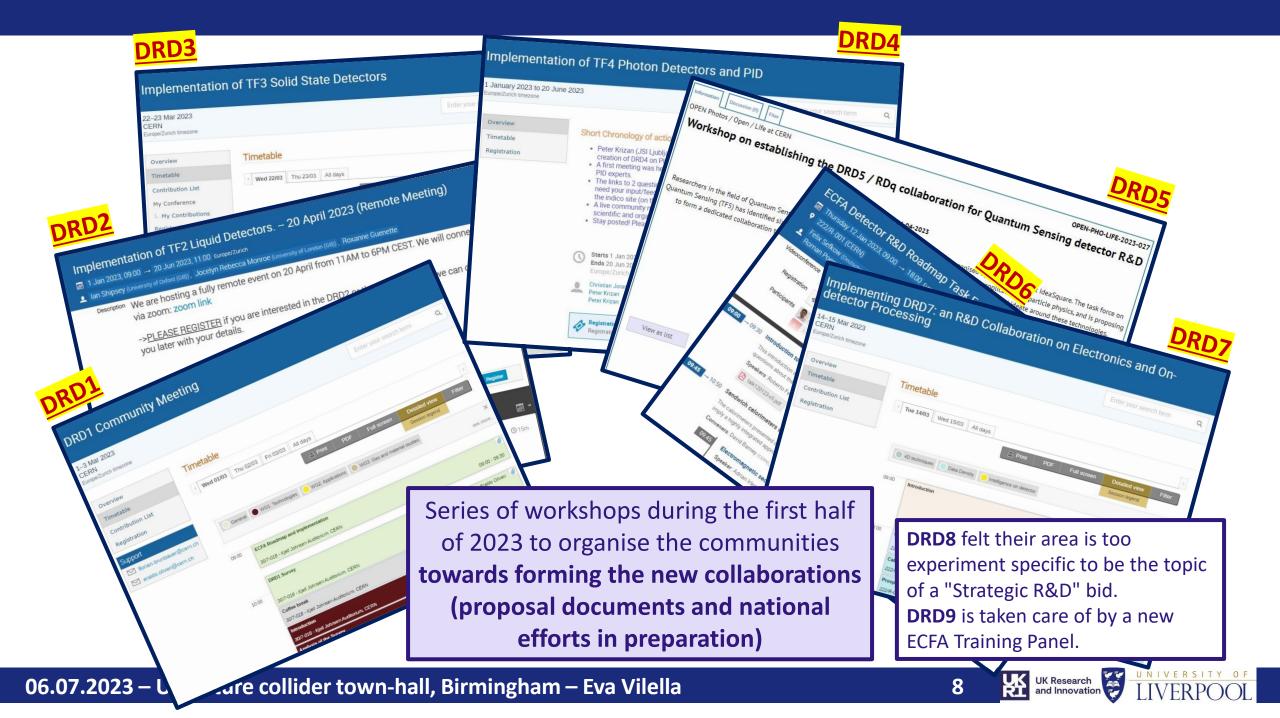
# Solid state detectors (TF3) – An example

Challenging specifications

Staged R&D programme

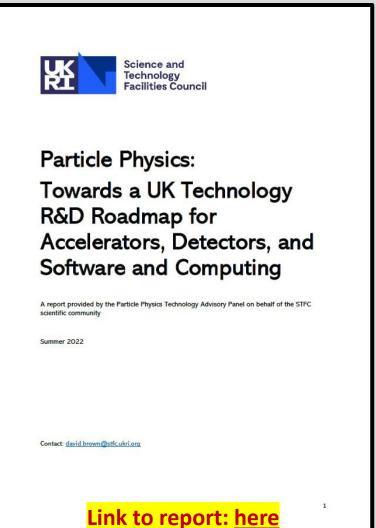
Stepping stones

| "Technical" Start Date |                                | < 2030               |                   |                                  | 2030 -2035                                  |  | 2035 -2040                                     | 2035 -2040 2040 - 2045                                       |                                       | CL   |              |  |  |
|------------------------|--------------------------------|----------------------|-------------------|----------------------------------|---|--|--|--|---------------------------------------|--|--------------|--|--|
|                        |                                | ALICE LS3            | Belle II<br>CBM   | NA62                             | LHCb, ATLAS, CMS<br>(≥ LS4) <sup>7)</sup>   | ALICE 3 - EIC  | ILC  | FCC-ee   | cuc                                   | Steppi   | ng ston      |  |  |
| MAPS                   | technology node <sup>1)</sup>  | 65 nm -<br>stitching | 65 nm - stitching |                                  |   | 28   | nm   | ≲ 28 nm  |                                       | ≃ 10 nm  | ≲ 28 nm      |  |  |
|                        | -1-1                           | 10 - 20 μm           | 10 - 20 μm        |                                  |   |  | pitch ≤ 10 μm for α <sub>ht</sub> ≤ 3 μm in VD |  |                                       |  |              |  |  |
|                        | pitch                          |                      |                   |                                  |   | Reduce z-granularity in TK - pad granularity in analog Cal.  |  |  |                                       |  |              |  |  |
|                        | wafer size <sup>2)</sup>       | 12"                  | 12"               |                                  | 12"   |  |  |  |                                       |  |              |  |  |
|                        | rate <sup>3)</sup>             |                      |                   | (                                | O(100) MHz/cm <sup>2</sup>                  |  |  |  | 5 GHz/cm <sup>2</sup>                 | 30 GHz/cm <sup>2</sup>                                   |              |  |  |
|                        | ultrafast timing <sup>4)</sup> |                      |                   |                                  |   | $\sigma_t \le 100 \text{ ps}$  |  |  |                                       | σ <sub>t</sub> ≤ 20 ps                                   |              |  |  |
|                        | radiation tolerance            |                      |                   |                                  | 3 x 10 <sup>15</sup> neq/cm <sup>2</sup>    |  |  |  |                                       | 10 <sup>18(16)</sup> neq/cm <sup>2</sup><br>VD/Cal.(Trk) |              |  |  |
|                        | technology node1)              |                      |                   |                                  | ASIC 28 nm                                  | ASIC 2   | 28 nm  | ASIC ≲   | 28 nm                                 | ASIC ≈ 10 nm   | ASIC ≤ 28 nm |  |  |
| 8                      |                                |                      |                   |                                  | ≲ 25 µm in VD                               |  |  | ≲ 10 ;   | ım for q <sub>it</sub> ≲3 μr          | n in VD  |              |  |  |
| Ö                      | pitch                          |                      |                   |                                  |   |  | 5  | ≤ 50 μm for q <sub>it</sub> ≲                                | 10 μm in Trk                          |  |              |  |  |
| ssiv                   | wafer size <sup>2)</sup>       |                      |                   |                                  | 12"   |  |  |  |                                       |  |              |  |  |
| /Pa                    | rate <sup>3)</sup>             |                      |                   |                                  | 6 GHz /cm <sup>2</sup>                      |  |  |  |                                       | 30 GHz/cm <sup>2</sup>                                   |              |  |  |
| r/3E                   | ultrafast timing <sup>4)</sup> |                      |                   | σ, ≃ !                           |   | 50 - 100 ps  |  | $\sigma_{\rm t} \lesssim 100~{\rm ps}$                       |                                       | σ <sub>t</sub> ≤ 20 ps                                   |              |  |  |
| Planar/3D/Passive CMOS | radiation tolerance            |                      |                   |                                  | 6 x 10 <sup>16</sup> neq/cm <sup>2</sup>    |  |  |  |                                       | 10 <sup>18(16)</sup> neq/cm <sup>2</sup><br>VD/Cal.(Trk) |              |  |  |
|                        | technology node <sup>1)</sup>  |                      |                   |                                  |   |  | ASIC 28 nm                                     | ASIC ≤ 28 nm   |                                       | ASIC ≈ 10 nm   |              |  |  |
|                        | pitch                          |                      |                   | ≃ 300 µm<br>(100% fill<br>facor) | ≲ 50 µm<br>(100% fill facor)                | same as for other technologies with ultimate pitch $\lesssim 10~\mu m$ for $q_{st} \lesssim 3~\mu m$ in VD |  |  |                                       |  | n VD         |  |  |
| Ds                     | wafer size <sup>2)</sup>       |                      |                   |                                  | > 3"  | 12"  |  |  |                                       |  |              |  |  |
| LGADs                  | rate <sup>3)</sup>             |                      |                   |                                  | 6 GHz /cm <sup>2</sup>                      |  |  |  |                                       | 30 GHz/cm <sup>2</sup>                                   |              |  |  |
| 1                      | ultrafast timing <sup>4)</sup> |                      |                   |                                  | $\sigma_t \le 30 \text{ ps}$                | $\sigma_t \approx 20 \text{ ps (PID)}$   | $\sigma_t \le 20 \text{ ps}$<br>VD/Trk/Cal.    | $\sigma_t \stackrel{<}{\scriptstyle \sim} 10 \text{ ps PID}$ | σ <sub>t</sub> ≤ 20 ps<br>VD/Trk/Cal. | σ <sub>t</sub> ≤ 20 ps VD/T                              | rk/Cal.      |  |  |
|                        | radiation tolerance            |                      |                   |                                  | $\gtrsim 5 \times 10^{15} \text{ neq/cm}^2$ |  |  |  |                                       | 10 <sup>18(16)</sup> neq/cm <sup>2</sup><br>VD/Cal.(Trk) |              |  |  |
| backend<br>processing  | sensor thickness <sup>5)</sup> | < 50 μm MAPS         | < 50 μm MAPS      |                                  | < 150 µm<br>Plan/3D/Pas.<br>< 50 µm LGADs   | < 50 μm MAPS, Planar/3D/Passive CMOS, LGADs  |  |  |                                       |  |              |  |  |
| pro<br>pro             | 3D integration <sup>6)</sup>   |                      |                   |                                  |   |  |  |  |                                       |  |              |  |  |



# **UK Particle Physics Technology Advisory Panel (PPTAP)**

- Developed by the STFC scientific community
- To coordinate the UK response to the European Committee on Future Accelerators (ECFA) and European Laboratory Directors Group (ELDG) R&D roadmaps
- To provide a report for STFC's Technology and Accelerator Advisory Board (TAAB) on developing a coherent response to the European activities



# PTAP report

### Strengths

Multiple including, beam dynamics, RF systems, beam instrumentation, feedback and control, plasma, surface science

ERL, muons, permanent magnets, thin-film SRF, mm-wave & THz, particle sources

Multiple including DAQ, Silicon, Quantum

Well-established expertise

Leadership roles

Training and hands-on opportunities

Well-established track record of R&D in a number of areas

Strong input into R&D roadmaps

Integration

Software and computing expertise

### Weaknesses

Links with industry under-developed Discontinuity in funding projects

Approach to dependencies not joined up (performance requirements)

Lack of investment in electronics

Quantum – no project/facility to scale up

Lack of access to R&D facilities/beamlines
Disparate small groups in some areas (novel acceleration, calorimetry, integration,
gaseous detectors)
Lack of career paths for technical experts
Lack of coordinated computing & software training
Little early TRL collaboration with industry

### Opportunities

Expertise in areas of growing importance (thin film, ERL, permanent magnets, MM-wave, sustainable design)

STFC facilities (CLARA, EPAC) leading to international opportunities (EuPRAXIA) Future UK facilities (UK XFEL, ISIS II)

Expertise in essential, as yet unfilled and needed, areas

International R&D underway

Low-cost test stands and bench-top experiments

Long-standing experienced communities (DAQ, integration, beam dynamics)

Leadership building from expertise (muon, ERL, beam dynamics)

Partnership with industry

Greater coordination of computing and software training and expertise

### Obstacles

Little UK R&D underway

Funding – often just project related, lack of investment for co-creation and early-

stage R&D

Industry not well plugged in Overall cost of end goal

Sustainability of end goal

Accelerators

Detectors

Both



# The PPTAP report... (my take-home messages)

- ... encourages a shift from the current funding model of experiment-construction-project driven Accelerators, Detectors, Software and Computing technology R&D to that of technology R&D driven programmes.
  - A desire for longer-term stable funding for technology R&D
  - A different and broader approach to detector R&D to complement the construction project funding might be beneficial
- ... notes that the traditional approach that understandably focuses on the science drivers, and the projects delivering these, were missing the opportunities of creating technology synergies that could enhance science delivery, skills development, and career trajectories. The financial constraints of recent years have further aggravated this by concentrating R&D into construction projects, where there is limited time and capacity, thereby restricting cross fertilisation, and potentially squeezing out early-stage innovation.
- ... says that **cross-experimental R&D projects can be beneficial**, allowing the sharing of expertise and producing enhanced solutions for the same cost.

# **Early-stage R&D**



### PRD call for applications 2015

STFC has announced a call for applications to the Projects Research and Development scheme (PRD). Applications should be submitted by the deadline of July 29th2015 and will be reviewed at a meeting of the PPRP Panel on October 28/29 2015. STFC intends to allocate a total of around £1.0 Million. It is expected that most grants will start no earlier than 1 April 2016.

The PRD scheme is intended to develop the capabilities needed to underpin UK science and technology leadership in future Science and Technology Facilities Council projects and gives industry the opportunity, in collaboration with approved research organisations, to apply directly to the STFC for funding for research and development.

The PRD scheme provides funding for research and development projects which enable STFC to deliver the science programme objectives in the areas of particle physics, particle astrophysics, nuclear physics and astronomy. Please note that proposals for project specific R&D, or small upgrades for space instruments and missions, fall within the remit of the UK Space Agency.

More details of the STFC PRD scheme, including an updated guide for applicants can be found on our PRD webpage.

# Early-stage research and development scheme 2023

| Opportunity status: | Closed   |
|---------------------|--|
| Funders:            | Science and Technology Facilities Council (STFC) |
| Funding type:       | Grant  |
| Maximum award:      | £600,000   |
| Publication date:   | 10 May 2023                                      |
| Opening date:       | 11 May 2023 9:00am UK time                       |
| Closing date:       | 1 June 2023 5:00pm UK time                       |

Apply for funding to the early-stage research and development scheme.

You must be based at a <u>UK research organisation eligible</u> for early-stage research and development funding and send an expression of interest notification.

The full economic cost of your project can be up to £600,000. STFC will fund 80% of the full economic cost.

Print this guidance or save as PDF

# Guidance on good research

Good research resource hub

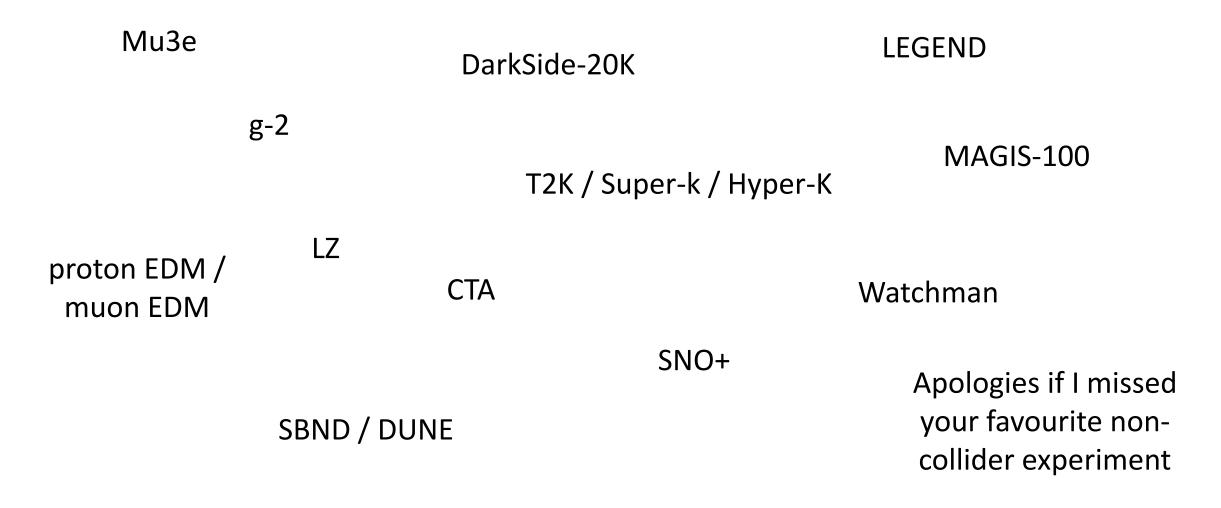
## Subscribe to UKRI emails

Sign up for news, views,





# Non-collider experiments... don't shoot me



# My concerns

- We are safe (?) until ~2035... then what?
- What do we need to do now to be safe then?
- Concentrate on R&D for the next big thing?
- Look for smaller non-collider experiments?
- Money
  - Also for blue-sky detector R&D
- People
  - How do we maintain our very much skilled hardware people?
  - How do we transfer their knowledge and expertise to the next generation?
  - How do we keep the next generation interested?